

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	((("6903278") or ("5888849")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2010/11/08 09:28
L2	2819	428/901.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/08 09:35
L3	201	174/546.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/08 09:36
L4	1539	361/748.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/08 09:36
S310	330	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S311	32	("4891687" "5929517" "5973389" "6020221" "6279758" "6284569" "6303985" "6326544" "6426565" "6440777" "6486562" "6517662" "6519843" "6584897" "6599365" "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S312	2	("4710419").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S313	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S314	127	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50

S315	670	257/667.ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S316	4520	257/787.ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S317	4014	257/678.ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S318	4166	257/778.ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S319	392	(257/e23.001).ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S320	280	(257/e23.18).ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S321	1832	(257/e23.039).ccls.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S322	12505	spray\$3 near3 mold\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S323	421	S322 and semiconductor and substrate	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S324	330	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50

S325	8	semiconductor and (plastic near2 stiffener) near10 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S326	9	substrate and spool and (index adj hole\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S327	483	substrate and (index adj hole \$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S328	474	S327 not S326	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S329	220	S328 and @ad<="20011231"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S330	260	S328 and @ad<="20021231"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S331	230	S328 and @ad<="20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S332	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2010/10/05 11:50
S333	235	((cobbley near2 chad) (baerlocher near2 cary)).inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S334	48148	(micron).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S338	47	substrate with (stiffener dam support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50

S340	31	S338 and @ad<="20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S341	96	substrate with (stiffener dam support cas\$3 wall)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S342	49	S341 not S338	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S343	36	S342 and @ad<="20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S344	134	substrate with (stiffener dam support\$4 cas\$3 wall sidewall)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S345	38	S344 not S341	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S346	26	S345 and @ad<="20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:50
S347	16	(mold\$3 near\$ apparatus) same substrate same (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/05 11:53
S348	2393	(board support substrate) with (plastic mold\$3) with (stiffner dam protrusion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:40
S349	1166	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:49

S350	3441	257/676.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:49
S351	719	257/e31.118.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:49
S352	2826	257/e21.499.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:49
S353	4993	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:50
S355	873	438/112.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:50
S356	2317	438/123.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/10/07 10:50

11/ 8/ 10 9:36:26 AM

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